

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00153	0.51	0.09129
	Doped silicon	Silicon (Si)	7440-21-3	0.2985	99.49	17.80871
		Subtotal		0.30003	100	17.9
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.36875	100.0	22
		Subtotal		0.36875	100	22
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02006	0.03	1.197
	Copper alloy	Iron (Fe)	7439-89-6	0.06688	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.79143	99.87	3,984.813
		Subtotal		66.87837	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.08421	6.5	124.345
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.13036	16.0	306.08
	Filler	Silica fused	60676-86-0	22.76597	71.0	1,358.23
	Flame retardant	Metal hydroxide		2.08421	6.5	124.345
		Subtotal		32.06475	100	NaN
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01069	5.0	0.63772
	Lead alloy	Silver (Ag)	7440-22-4	0.00534	2.5	0.31886
	Lead alloy	Lead (Pb)	7439-92-1	0.19775	92.5	11.79785
		Subtotal		0.21378	100	12.75443
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.17432	100.0	10.4
		Subtotal		0.17432	100	10.4
		Total		100	100	NaN

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